



VERSION WITH MARKINGS TO SHOW CHANGES MADE

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In the Claims:

Please amend claim 7 as follows:

7. (Amended) A process of production of a semiconductor apparatus comprising:

a first step of forming metal ball bumps [so as to connect to] in direct contact with a circuit pattern of a semiconductor device,

a second step of forming a resin film on a circuit pattern forming surface of said semiconductor device so as to seal spaces between said metal ball bumps and to become thinner than a height of the metal ball bumps, and

a third step of cleaning the surfaces of the metal ball bumps projecting out from the resin film.

Please cancel claim 9.

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